MOSFET Silicon N-Channel MOS

1. Applications

Synchronous rectification in SMPS,
Hard switching and High speed circuit
DC/DC in telecoms and industrial

2. Features

Low drain-source on-resistance: RDS(on)=4.1mΩ (typ.)
High speed power switching
Enhanced body diode dv/dt capability
Enhanced avalanche ruggedness

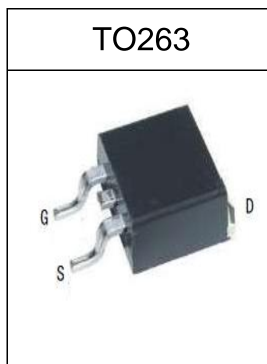
Table 1 Key Performance Parameters

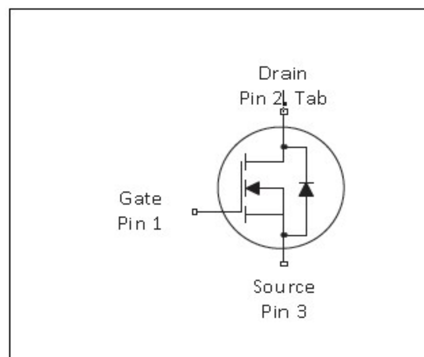
Parameter	Value	Unit
V_{DS} @ $T_{j,max}$	100	V
$R_{DS(on),max}$	4.5	mΩ
$Q_{g,typ}$	97.3	nC
$I_{D,pulse}$	486	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
AUB045N10BT	TO263	AUB045N10BT

TO263





1 Maximum ratings

At T_j= 25°C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current at sikicon[1)]	I_D		-	176	A	T_C=25°C
Continuous drain current at package[1)]	I_D		-	123	A	T_C=25°C
Continuous drain current at silicon[1)]	I_D			112	A	T_C=100°C
Pulsed drain current[2)]	$I_{D,pulse}$	-		486	A	T_C=25°C
Avalanche energy, single pulse	E_{AS}	-	-	441	mJ	Tc=25°C,VDD=50V,Vgs=10V, L=0.5mH, RG=25Ω
Avalanche current, single pulse	I_{AR}	-	-	42	A	Tc=25°C, VDD=50V, L=0.5mH, RG=25Ω
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Power dissipation	P_{tot}	-	-	229	W	T_C=25°C
Storage temperature	T_{stg}	-55	-	150	°C	
Operating junction temperature	T_j	-55	-	150	°C	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			260	°C	

1) Limited by $T_{j,max}$. Maximum Duty Cycle D = 0.50
2) Pulse width t_p limited by $T_{j,max}$
3) Identical low side and high side switch with identical R_G

2 Thermal characteristics

Table Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.54	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

3 Electrical characteristics

at T_j=25°C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{(GS)th}$	2.5	2.9	4.5	V	V_{DS}=V_{GS}, I_D=250uA
Zero gate voltage drain current	I_{DSS}	-	-	1	uA	V_{DS}=100V, V_{GS}=0V, T_j=25°C
Gate-source leakage current	I_{GSS}	-	-	+/-100	nA	V_{GS}=+/-20V, V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	4.1	4.5	mΩ	V_{GS}=10V, I_D=20A, T_j=25°C
Gate resistance (Intrinsic)	R_G	-	1.6	-	Ω	f=1MHz, open drain
Transconductance	Gfs		93.2		S	V_{DS}=5V, I_D=50A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	5763	-	PF	V_{GS}=0V, V_{DS}=50V, f=1MHz
Output capacitance	C_{oss}	-	485.1	-	PF	V_{GS}=0V, V_{DS}=50V, f=1MHz
Reverse transfer capacitance	C_{rss}	-	22.4	-	PF	V_{GS}=0V, V_{DS}=50V, f=1MHz
Turn-on delay time	$t_{d(on)}$	-	16.6	-	ns	V_{DD}=50V, V_{GS}=10V, I_D=50A, R_G=3Ω
Rise time	t_r	-	74	-	ns	V_{DD}=50V, V_{GS}=10V, I_D=50A, R_G=3Ω
Turn-off delay time	$t_{d(off)}$	-	51	-	ns	V_{DD}=50V, V_{GS}=10V, I_D=50A, R_G=3Ω
Fall time	t_f	-	53	-	ns	V_{DD}=50V, V_{GS}=10V, I_D=50A, R_G=3Ω

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	20.9	-	nC	V_{DD}=50V, I_D=20A, V_{GS}=10V
Gate to drain charge	Q_{gd}	-	29.1	-	nC	V_{DD}=50V, I_D=20A, V_{GS}=10V
Gate charge total	Q_g	-	97.3	-	nC	V_{DD}=50V, I_D=20A, V_{GS}=10V

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous Source Current at silicon	I_{SD}	-	-	176	A	*Maximum Ratings*
Diode forward voltage	V_{SD}	-	-	1.2	V	V_{GS}=0V, I_s=1A, T_j=25°C
Reverse recovery time	t_{rr}	-	79	-	ns	*Vgs=0V*, I_F=50A, di_F/dt=100A/μs
Reverse recovery charge	Q_{rr}	-	141	-	nC	*Vgs=0V*, I_F=50A, di_F/dt=100A/μs
Peak Reverse Recovery Current	I_{rrm}	-	3.01	-	A	*Vgs=0V*, I_F=50A, di_F/dt=100A/μs

4 Electrical characteristics diagram

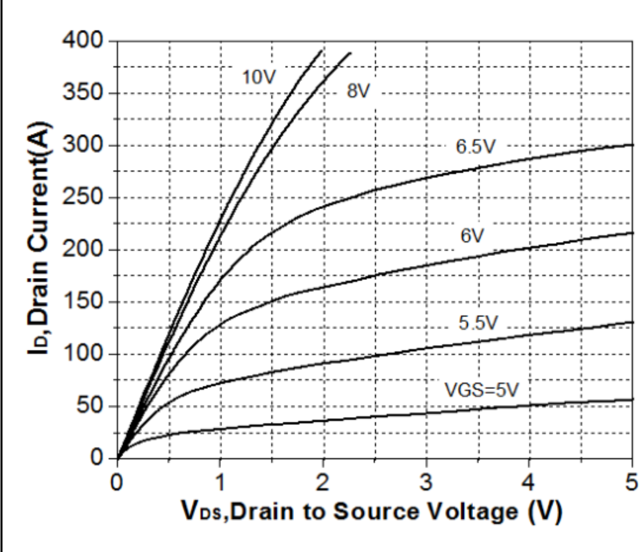
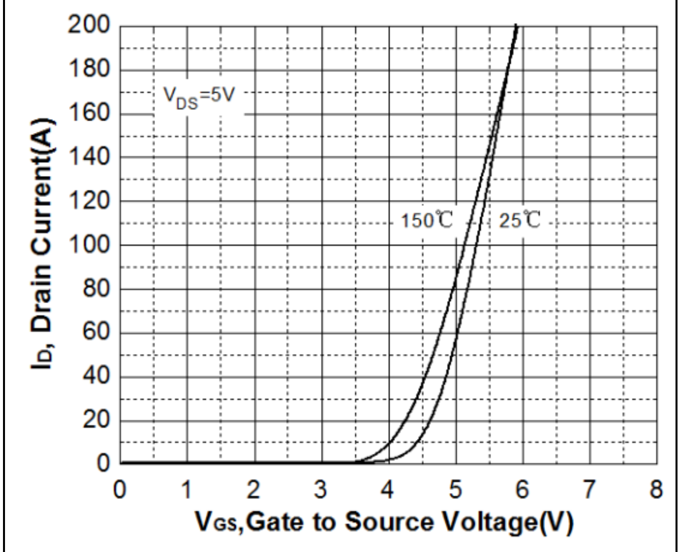
Diagram 1: Typ. Output characteristics	Diagram 2: Typ. Transfer characteristics
	
I_D=f(V_{DS}); T_j=25 °C; parameter: V_{GS}	I_D=f(V_{GS});parameter: T_j

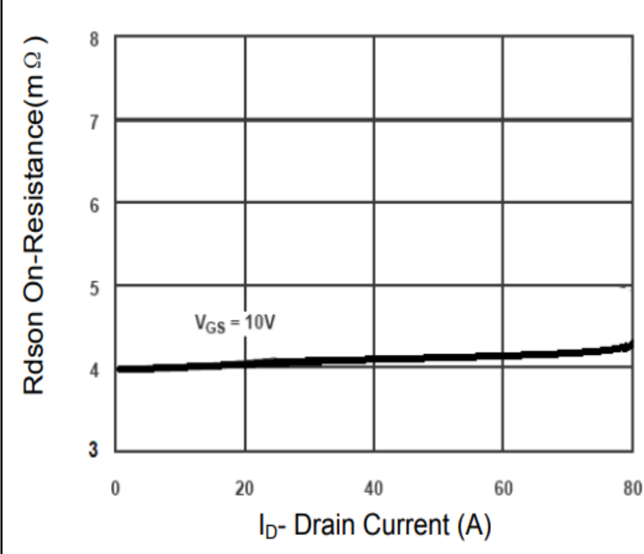
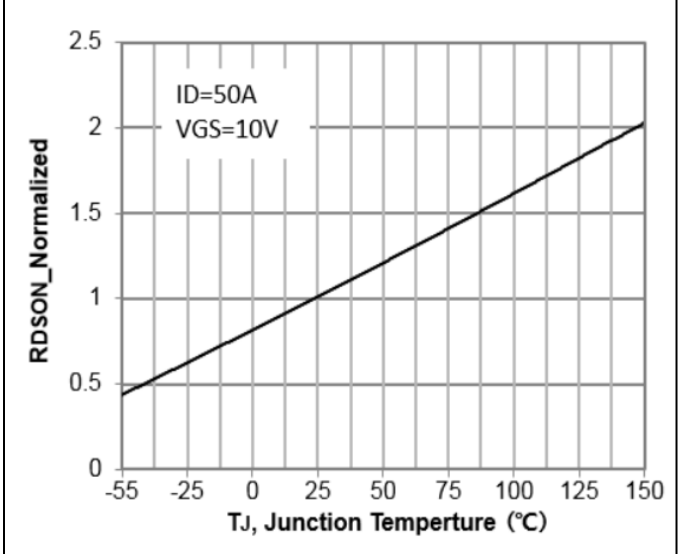
Diagram 3: Typ. Rdson vs. Drain Current	Diagram 4: Typ. Rdson – Junction Temperature
	
$R_{ds(on)}$=f(Id);Vgs=10V	$R_{ds(on)}$=f(T_j);Vgs=10V/I_D=50A

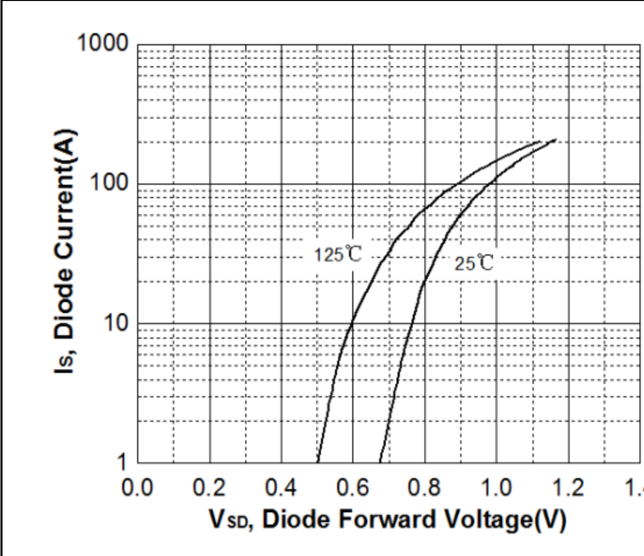
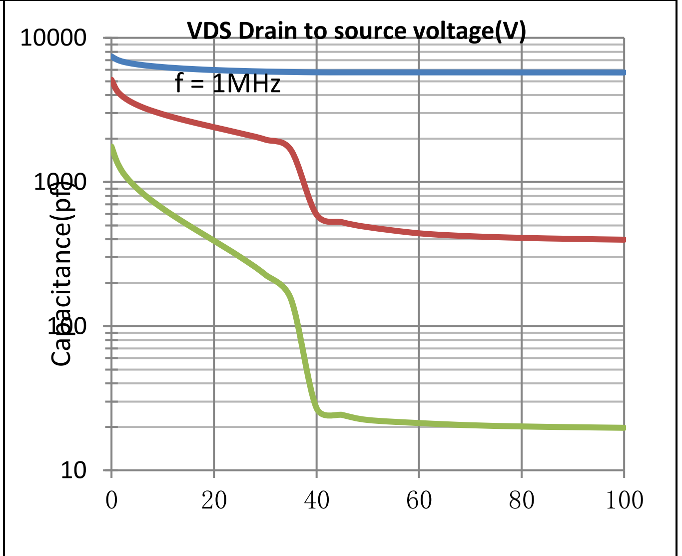
Diagram 5: Typ. Body-Diode Characteristics	Diagram 6: Typ. Capacitance vs. Vds
	
I_F=f(V_{DS});parameter: Tj	C=f(V_{DS}); V_{GS}=0V; f=1MHz

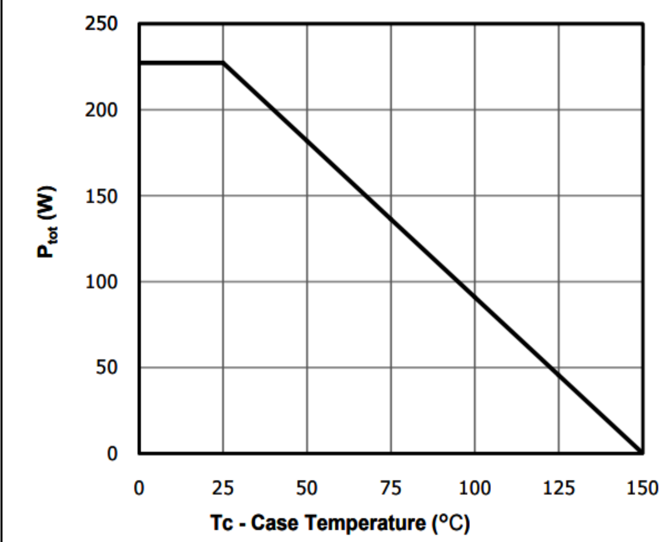
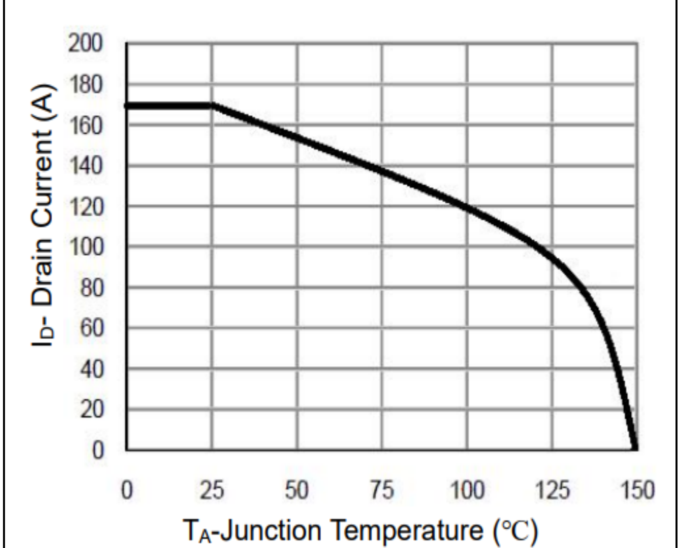
Diagram 7: Typ. Power Dissipation	Diagram 8: Typ. Drain Current De-rating
	
P_{tot}=f(T_C);	Id=f(T_C);

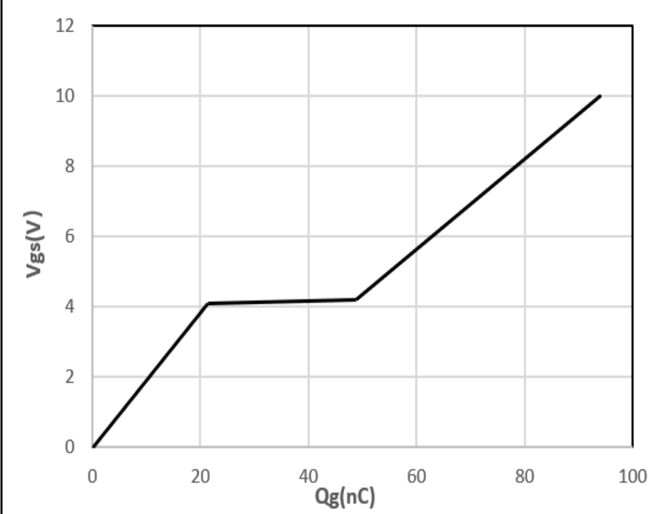
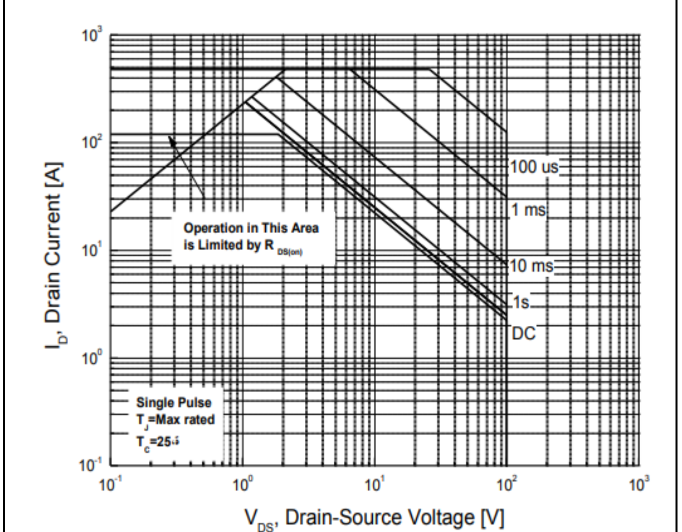
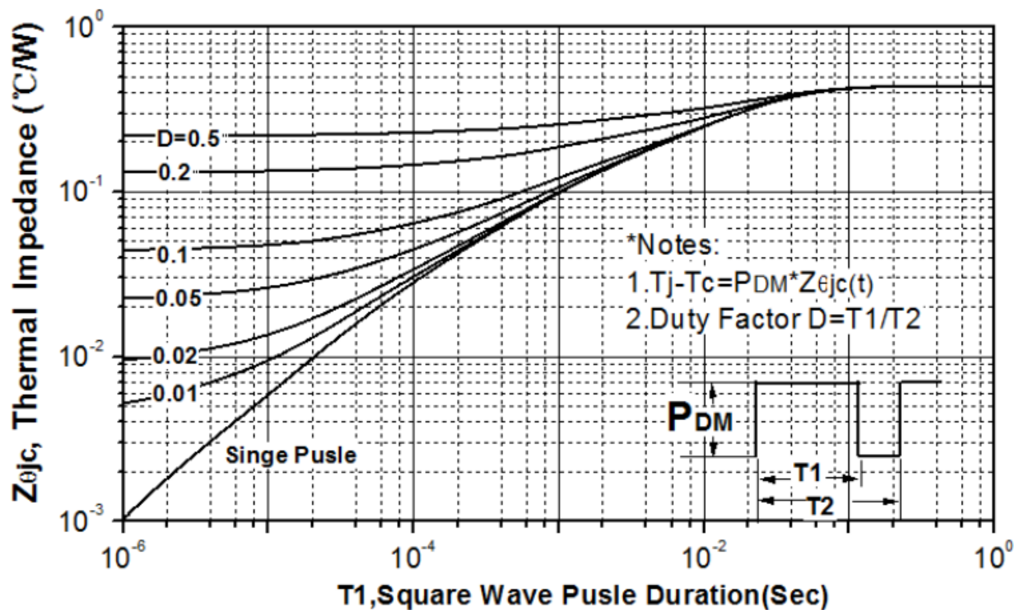
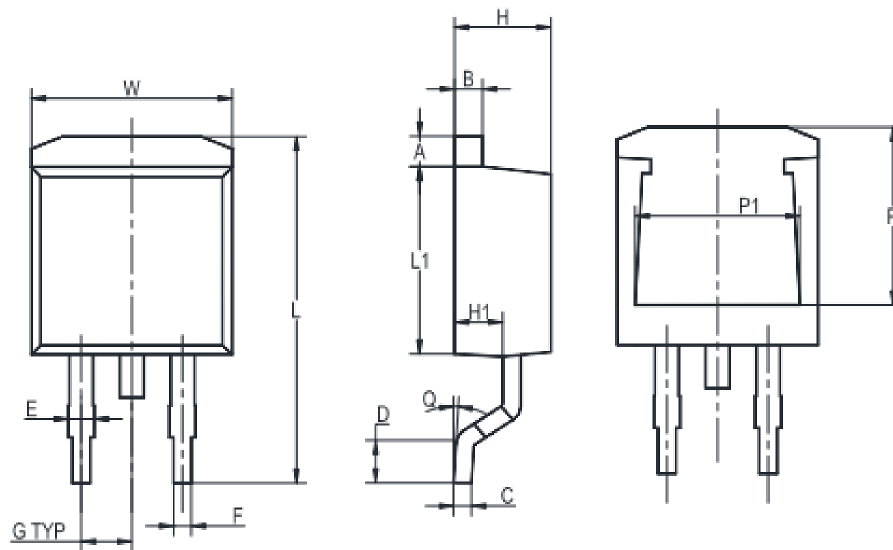
Diagram 9: Typ. Gate charge	Diagram 10: Typ. Maximum Safe Operating Area
	
V_{GS}=f(Q_{gate}); I_D=20A pulsed; parameter: V_{DD}	I_D=f(V_{DS}); T_C=25 °C; V_{GS}> 7V; D=0; parameter tp

Figure 11 Normalized Maximum Transient Thermal Impedance



5. Package Outlines



UNIT	A	B	C	D	E	F	G	W	H	H1	L	L1	Q	P	P1
mm	1.5	1.5	0.5	2.60	1.6	0.94	2.54	10.5	4.8	2.9	16.5	8.7	8°	7.6	8.2
	1.1	1.1	0.3	2.15	1.1	0.68	TYP	9.6	4.4	2.5	14.5	8.2	MAX	7.1	7.4

Figure1：Outline PG-TO263(HC&LM)

Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2023-05-12	Preliminary version